

17W 2811



February 23, 2005

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	09/621,546	03/30/2001
J. Y. LEE	09/821546	
"A STRUCTURE AND MANUFACTURING METHOD OF CHIP SCALE PACKAGE"		
Grp. Art Unit: 2811	D. W. OWENS	

RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Office Action dated September 23, 2004, please amend the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on February 23, 2005.

George O. Saile, Reg. No. 19,572

Signature

Date

George O. Saile
2/23/05

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 29 of this paper.